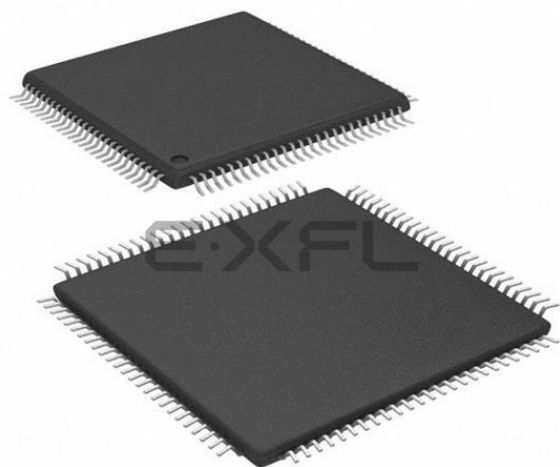




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Details

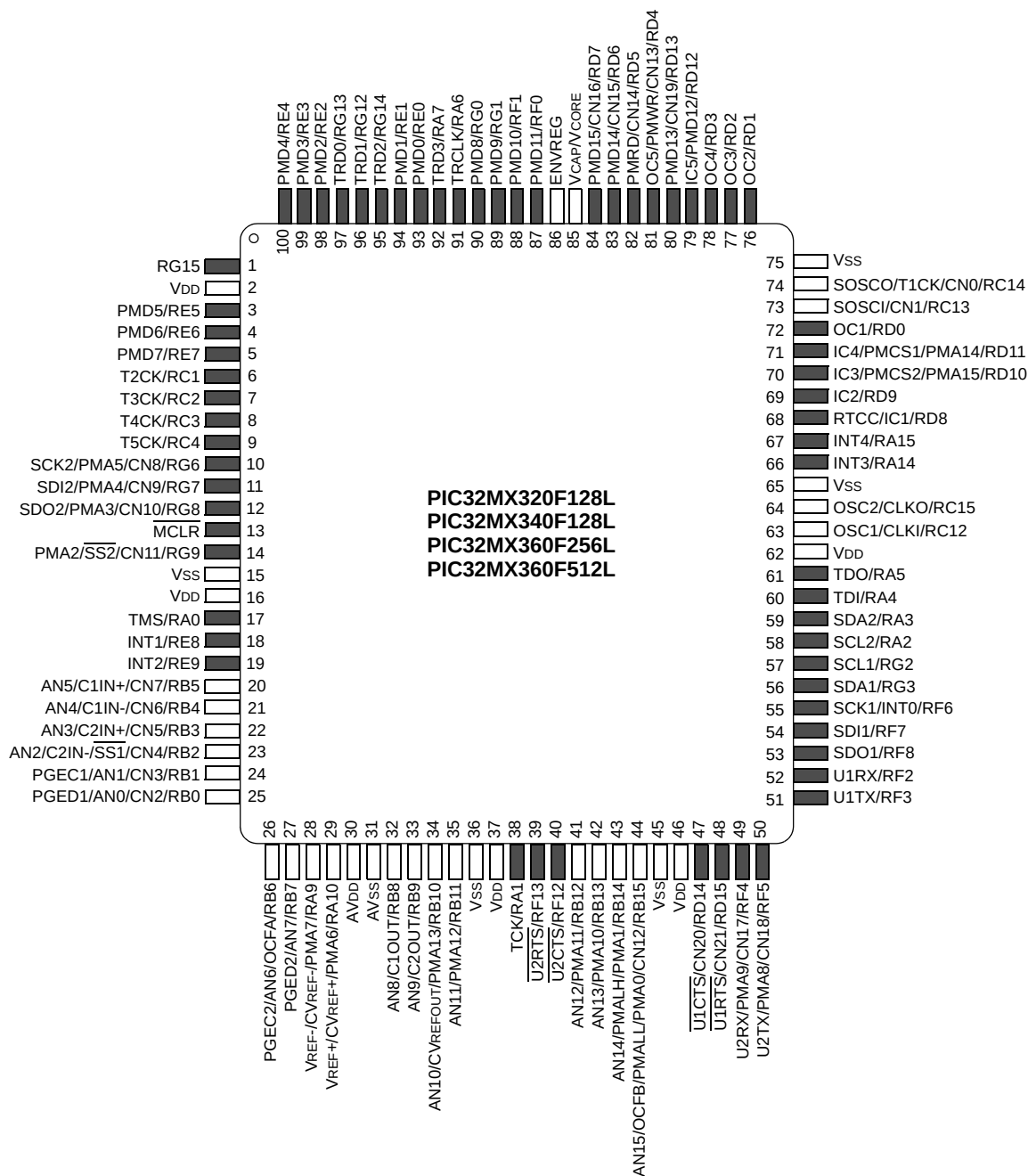
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx440f128lt-80v-pt

PIC32MX3XX/4XX

Pin Diagrams (Continued)

100-Pin TQFP (General Purpose)

■ = Pins are up to 5V tolerant



Pin Diagrams (Continued)

121-Pin XBGA⁽¹⁾

● = Pins are up to 5V tolerant

PIC32MX320F128L
PIC32MX340F128L
PIC32MX360F256L
PIC32MX360F512L

	1	2	3	4	5	6	7	8	9	10	11
A	● RE4	● RE3	● RG13	● RE0	● RG0	● RF1	○ ENVREG	○ Vss	● RD12	● RD2	● RD1
B	● NC	● RG15	● RE2	● RE1	● RA7	● RF0	○ Vcore/ VCAP	● RD5	● RD3	○ Vss	○ RC14
C	● RE6	○ VDD	● RG12	● RG14	● RA6	● NC	● RD7	● RD4	○ VDD	○ RC13	● RD11
D	● RC1	● RE7	● RE5	○ Vss	○ Vss	● NC	● RD6	● RD13	● RD0	● NC	● RD10
E	● RC4	● RC3	● RG6	● RC2	○ VDD	● RG1	○ Vss	● RA15	● RD8	● RD9	● RA14
F	● MCLR	● RG8	● RG9	● RG7	○ Vss	● NC	● NC	○ VDD	○ RC12	○ Vss	○ RC15
G	● RE8	● RE9	● RA0	● NC	○ VDD	○ Vss	○ Vss	● NC	● RA5	● RA3	● RA4
H	○ RB5	○ RB4	○ Vss	○ VDD	● NC	○ VDD	● NC	● RF7	● RF6	● RG2	● RA2
J	○ RB3	○ RB2	○ RB7	○ AVDD	○ RB11	○ RA1	○ RB12	● NC	● NC	● RF8	○ RG3
K	○ RB1	○ RB0	○ RA10	○ RB8	● NC	● RF12	○ RB14	○ VDD	● RD15	● RF3	● RF2
L	○ RB6	○ RA9	○ AVss	○ RB9	○ RB10	● RF13	○ RB13	○ RB15	● RD14	● RF4	● RF5

Note 1: Refer to Table 3 for full pin names.

TABLE 3-1: MIPS® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul <i>rt</i>) (div <i>rs</i>)	Latency	Repeat Rate
MULT/MULTU, MADD/MADDU, MSUB/MSUBU	16 bits	1	1
	32 bits	2	2
MUL	16 bits	2	1
	32 bits	3	2
DIV/DIVU	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

The MIPS architecture defines that the result of a multiply or divide operation be placed in the HI and LO registers. Using the Move-From-HI (MFHI) and Move-From-LO (MFLO) instructions, these values can be transferred to the general purpose register file.

In addition to the HI/LO targeted operations, the MIPS32 architecture also defines a multiply instruction, MUL, which places the least significant results in the primary register file instead of the HI/LO register pair. By avoiding the explicit MFLO instruction, required when using the LO register, and by supporting multiple destination registers, the throughput of multiply-intensive operations is increased.

Two other instructions, multiply-add (MADD) and multiply-subtract (MSUB), are used to perform the multiply-accumulate and multiply-subtract operations. The MADD instruction multiplies two numbers and then adds

the product to the current contents of the HI and LO registers. Similarly, the MSUB instruction multiplies two operands and then subtracts the product from the HI and LO registers. The MADD and MSUB operations are commonly used in DSP algorithms.

3.2.3 SYSTEM CONTROL COPROCESSOR (CP0)

In the MIPS architecture, CP0 is responsible for the virtual-to-physical address translation, the exception control system, the processor's diagnostics capability, the operating modes (kernel, user and debug), and whether interrupts are enabled or disabled. Configuration information, such as presence of options like MIPS16e, is also available by accessing the CP0 registers, listed in Table 3-2.

TABLE 3-2: COPROCESSOR 0 REGISTERS

Register Number	Register Name	Function
0-6	Reserved	Reserved
7	HWREna	Enables access via the RDHWR instruction to selected hardware registers
8	BadVAddr ⁽¹⁾	Reports the address for the most recent address-related exception
9	Count ⁽¹⁾	Processor cycle count
10	Reserved	Reserved
11	Compare ⁽¹⁾	Timer interrupt control
12	Status ⁽¹⁾	Processor status and control
12	IntCtl ⁽¹⁾	Interrupt system status and control
12	SRSCtl ⁽¹⁾	Shadow register set status and control
12	SRSMap ⁽¹⁾	Provides mapping from vectored interrupt to a shadow set
13	Cause ⁽¹⁾	Cause of last general exception
14	EPC ⁽¹⁾	Program counter at last exception
15	PRId	Processor identification and revision
15	EBASE	Exception vector base register
16	Config	Configuration register
16	Config1	Configuration register 1
16	Config2	Configuration register 2
16	Config3	Configuration register 3

3.3 Power Management

The MIPS32® M4K® Processor Core offers a number of power management features, including low-power design, active power management and power-down modes of operation. The core is a static design that supports slowing or halting the clocks, which reduces system power consumption during idle periods.

3.3.1 INSTRUCTION-CONTROLLED POWER MANAGEMENT

The mechanism for invoking power-down mode is through execution of the WAIT instruction. For more information on power management, see **Section 25.0 “Power-Saving Features”**.

3.3.2 LOCAL CLOCK GATING

The majority of the power consumed by the PIC32MX3XX/4XX family core is in the clock tree and clocking registers. The PIC32MX family uses extensive use of local gated-clocks to reduce this dynamic power consumption.

3.4 EJTAG Debug Support

The MIPS32® M4K® Processor Core provides for an Enhanced JTAG (EJTAG) interface for use in the software debug of application and kernel code. In addition to standard user mode and kernel modes of operation, the core provides a Debug mode that is entered after a debug exception (derived from a hardware breakpoint, single-step exception, etc.) is taken and continues until a debug exception return (DERET) instruction is executed. During this time, the processor executes the debug exception handler routine.

The EJTAG interface operates through the Test Access Port (TAP), a serial communication port used for transferring test data in and out of the core. In addition to the standard JTAG instructions, special instructions defined in the EJTAG specification define what registers are selected and how they are used.

TABLE 4-6: INTERRUPT REGISTERS MAP FOR THE PIC32MX420F032H DEVICE ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>			—	—	—	CS1IP<2:0>			CS1IS<1:0>	0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>			—	—	—	CTIP<2:0>			CTIS<1:0>	0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>			—	—	—	OC1IP<2:0>			OC1IS<1:0>	0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>			—	—	—	T1IP<2:0>			T1IS<1:0>	0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>			—	—	—	OC2IP<2:0>			OC2IS<1:0>	0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>			—	—	—	T2IP<2:0>			T2IS<1:0>	0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>			—	—	—	OC3IP<2:0>			OC3IS<1:0>	0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>			—	—	—	T3IP<2:0>			T3IS<1:0>	0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>			—	—	—	OC4IP<2:0>			OC4IS<1:0>	0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>			—	—	—	T4IP<2:0>			T4IS<1:0>	0000
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	OC5IP<2:0>			OC5IS<1:0>	0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>			—	—	—	T5IP<2:0>			T5IS<1:0>	0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>			—	—	—	CNIP<2:0>			CNIS<1:0>	0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>			—	—	—	U1IP<2:0>			U1IS<1:0>	0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>			—	—	—	CMP2IP<2:0>			CMP2IS<1:0>	0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>			—	—	—	PMP1P<2:0>			PMP1IS<1:0>	0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>			—	—	—	FSCMIP<2:0>			FSCMIS<1:0>	0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>			—	—	—	U2IP<2:0>			U2IS<1:0>	0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	USBIP<2:0>			USBIS<1:0>			—	—	—	FCEIP<2:0>			FCEIS<1:0>	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-10: I2C1-2 REGISTERS MAP⁽¹⁾

Virtual Address (BF80 #)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5000	I2C1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5010	I2C1STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D/A	P	S	R/W	RBF	TBF	0000
5020	I2C1ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5030	I2C1MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5040	I2C1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5050	I2C1TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5260	I2C1RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5200	I2C2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5210	I2C2STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D/A	P	S	R/W	RBF	TBF	0000
5220	I2C2ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5230	I2C2MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5240	I2C2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5250	I2C2TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
5260	I2C2RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table except I2CxRCV have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-13: ADC REGISTERS MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9110	ADC1BUFA	31:16	ADC Result Word A (ADC1BUFA<31:0>)																0000
		15:0																	0000
9120	ADC1BUFB	31:16	ADC Result Word B (ADC1BUFB<31:0>)																0000
		15:0																	0000
9130	ADC1BUFC	31:16	ADC Result Word C (ADC1BUFC<31:0>)																0000
		15:0																	0000
9140	ADC1BUFD	31:16	ADC Result Word D (ADC1BUFD<31:0>)																0000
		15:0																	0000
9150	ADC1BUFE	31:16	ADC Result Word E (ADC1BUFE<31:0>)																0000
		15:0																	0000
9160	ADC1BUFF	31:16	ADC Result Word F (ADC1BUFF<31:0>)																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

PIC32MX3XX/4XX

NOTES:

PIC32MX3XX/4XX

12.1 Parallel I/O (PIO) Ports

All port pins have three registers (TRIS, LAT and PORT) that are directly associated with their operation.

TRIS is a data direction or tri-state control register that determines whether a digital pin is an input or an output. Setting a TRISx register bit = 1 configures the corresponding I/O pin as an input; setting a TRISx register bit = 0 configures the corresponding I/O pin as an output. All port I/O pins are defined as inputs after a device Reset. Certain I/O pins are shared with analog peripherals and default to analog inputs after a device Reset.

PORT is a register used to read the current state of the signal applied to the port I/O pins. Writing to a PORTx register performs a write to the port's latch, LATx register, latching the data to the port's I/O pins.

LAT is a register used to write data to the port I/O pins. The LATx latch register holds the data written to either the LATx or PORTx registers. Reading the LATx latch register reads the last value written to the corresponding port or latch register.

Not all port I/O pins are implemented on some devices, therefore, the corresponding PORTx, LATx and TRISx register bits will read as zeros.

12.1.1 CLR, SET AND INV REGISTERS

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR or INV register, the base register must be read.

Note: Using a PORTxINV register to toggle a bit is recommended because the operation is performed in hardware atomically, using fewer instructions as compared to the traditional read-modify-write method shown below:

```
PORTC ^= 0x0001;
```

12.1.2 DIGITAL INPUTS

Pins are configured as digital inputs by setting the corresponding TRIS register bits = 1. When configured as inputs, they are either TTL buffers or Schmitt Triggers. Several digital pins share functionality with analog inputs and default to the analog inputs at POR. Setting the corresponding bit in the AD1PCFG register = 1 enables the pin as a digital pin.

The maximum input voltage allowed on the input pins is the same as the maximum V_{IH} specification. Refer to **Section 29.0 "Electrical Characteristics"** for V_{IH} specification details.

Note: Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

12.1.3 ANALOG INPUTS

Certain pins can be configured as analog inputs used by the ADC and Comparator modules. Setting the corresponding bits in the AD1PCFG register = 0 enables the pin as an analog input pin and must have the corresponding TRIS bit set = 1 (input). If the TRIS bit is cleared = 0 (output), the digital output level (V_{OH} or V_{OL}) will be converted. Any time a port I/O pin is configured as analog, its digital input is disabled and the corresponding PORTx register bit will read '0'. The AD1PCFG Register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

12.1.4 DIGITAL OUTPUTS

Pins are configured as digital outputs by setting the corresponding TRIS register bits = 0. When configured as digital outputs, these pins are CMOS drivers or can be configured as open drain outputs by setting the corresponding bits in the ODCx Open-Drain Configuration register.

The open-drain feature allows the generation of outputs higher than V_{DD} (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum V_{IH} specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

12.1.5 ANALOG OUTPUTS

Certain pins can be configured as analog outputs, such as the CVREF output voltage used by the comparator module. Configuring the Comparator Reference module to provide this output will present the analog output voltage on the pin, independent of the TRIS register setting for the corresponding pin.

12.1.6 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports (CNx) allows devices to generate interrupt requests in response to change of state on selected pin.

Each CNx pin also has a weak pull-up, which acts as a current source connected to the pin. The pull-ups are enabled by setting corresponding bit in CNPUE register.

15.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 15. “Input Capture”** (DS61122) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Input Capture module is useful in applications requiring frequency (period) and pulse measurement. The PIC32MX3XX/4XX devices support up to five input capture channels.

The Input Capture module captures the 16-bit or 32-bit value of the selected Time Base registers when an event occurs at the ICx pin. The events that cause a capture event are listed below in three categories:

1. Simple Capture Event modes
 - Capture timer value on every falling edge of input at ICx pin
 - Capture timer value on every rising edge of input at ICx pin

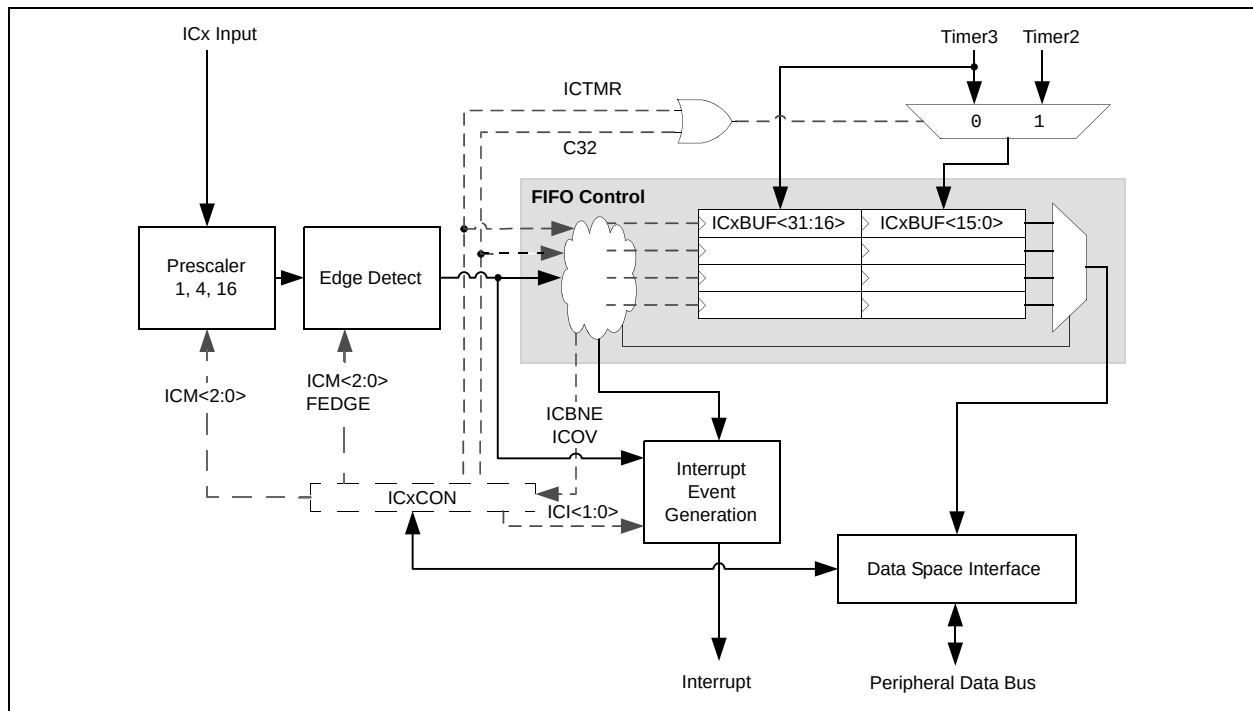
2. Capture timer value on every edge (rising and falling)
3. Capture timer value on every edge (rising and falling), specified edge first.
4. Prescaler Capture Event modes
 - Capture timer value on every 4th rising edge of input at ICx pin
 - Capture timer value on every 16th rising edge of input at ICx pin

Each input capture channel can select between one of two 16-bit timers (Timer2 or Timer3) for the time base, or two 16-bit timers (Timer2 and Timer3) together to form a 32-bit timer. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during CPU Sleep and Idle modes
- Interrupt on input capture event
- 4-word FIFO buffer for capture values
 - Interrupt optionally generated after 1, 2, 3 or 4 buffer locations are filled
- Input capture can also be used to provide additional sources of external interrupts

FIGURE 15-1: INPUT CAPTURE BLOCK DIAGRAM



PIC32MX3XX/4XX

NOTES:

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
JAL	Jump and Link	$GPR[31] = PC + 8$ $PC = PC[31:28] \parallel offset \ll 2$
JALR	Jump and Link Register	$Rd = PC + 8$ $PC = Rs$
JALR.HB	Jump and Link Register with Hazard Barrier	Like JALR, but also clears execution and instruction hazards
JR	Jump Register	$PC = Rs$
JR.HB	Jump Register with Hazard Barrier	Like JR, but also clears execution and instruction hazards
LB	Load Byte	$Rt = (\text{byte})Mem[Rs+offset]$
LBU	Unsigned Load Byte	$Rt = (\text{ubyte})Mem[Rs+offset]$
LH	Load Halfword	$Rt = (\text{half})Mem[Rs+offset]$
LHU	Unsigned Load Halfword	$Rt = (\text{uhalf})Mem[Rs+offset]$
LL	Load Linked Word	$Rt = Mem[Rs+offset]$ $LL_{bit} = 1$ $LLAdr = Rs + offset$
LUI	Load Upper Immediate	$Rt = \text{immediate} \ll 16$
LW	Load Word	$Rt = Mem[Rs+offset]$
LWPC	Load Word, PC relative	$Rt = Mem[PC+offset]$
LWL	Load Word Left	$Re = Re \text{ MERGE } Mem[Rs+offset]$
LWR	Load Word Right	$Re = Re \text{ MERGE } Mem[Rs+offset]$
MADD	Multiply-Add	$HI \mid LO += (\text{int})Rs * (\text{int})Rt$
MADDU	Multiply-Add Unsigned	$HI \mid LO += (\text{uns})Rs * (\text{uns})Rt$
MFC0	Move from Coprocessor 0	$Rt = CPR[0, Rd, sel]$
MFHI	Move from HI	$Rd = HI$
MFLO	Move from LO	$Rd = LO$
MOVN	Move Conditional on Not Zero	if $Rt \neq 0$ then $Rd = Rs$
MOVZ	Move Conditional on Zero	if $Rt = 0$ then $Rd = Rs$
MSUB	Multiply-Subtract	$HI \mid LO -= (\text{int})Rs * (\text{int})Rt$
MSUBU	Multiply-Subtract Unsigned	$HI \mid LO -= (\text{uns})Rs * (\text{uns})Rt$
MTC0	Move to Coprocessor 0	$CPR[0, n, Sel] = Rt$
MTHI	Move to HI	$HI = Rs$
MTLO	Move to LO	$LO = Rs$
MUL	Multiply with register write	$HI \mid LO = \text{Unpredictable}$ $Rd = ((\text{int})Rs * (\text{int})Rt)_{31..0}$
MULT	Integer Multiply	$HI \mid LO = (\text{int})Rs * (\text{int})Rd$
MULTU	Unsigned Multiply	$HI \mid LO = (\text{uns})Rs * (\text{uns})Rd$
NOP	No Operation (Assembler idiom for: SLL r0, r0, r0)	
NOR	Logical NOR	$Rd = \sim(Rs \mid Rt)$
OR	Logical OR	$Rd = Rs \mid Rt$
ORI	Logical OR Immediate	$Rt = Rs \mid \text{Immed}$
RDHWR	Read Hardware Register (if enabled by HWRE _{na} Register)	$Re = HWR[Rd]$

Note 1: This instruction is deprecated and should not be used.

28.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
 - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB C Compiler for Various Device Families
 - HI-TECH C for Various Device Families
 - MPASM™ Assembler
 - MPLINK™ Object Linker/
MPLIB™ Object Librarian
 - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
 - MPLAB SIM Software Simulator
- Emulators
 - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
 - MPLAB ICD 3
 - PICKit™ 3 Debug Express
- Device Programmers
 - PICKit™ 2 Programmer
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

28.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
 - Simulator
 - Programmer (sold separately)
 - In-Circuit Emulator (sold separately)
 - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
 - Source files (C or assembly)
 - Mixed C and assembly
 - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

PIC32MX3XX/4XX

FIGURE 29-5: EXTERNAL RESET TIMING CHARACTERISTICS

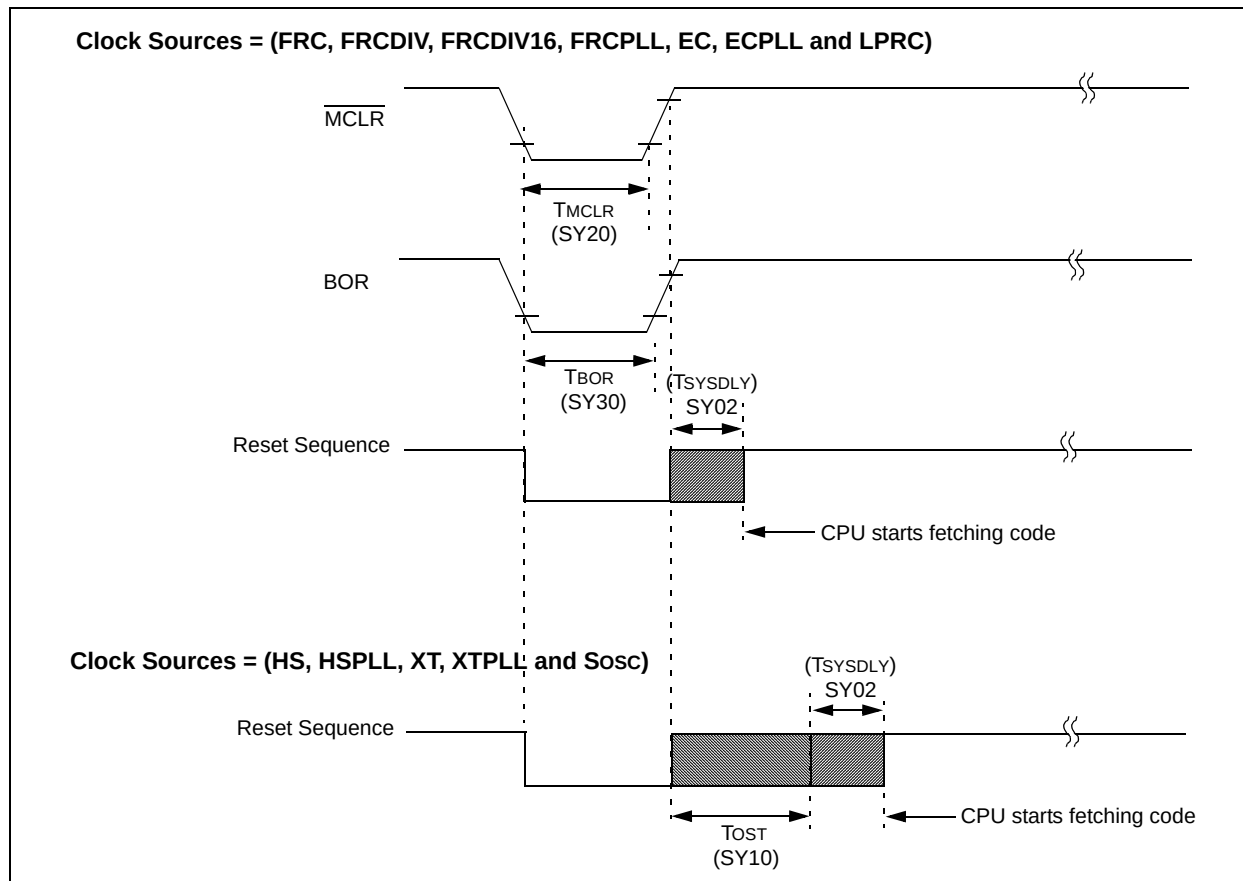


TABLE 29-22: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	μs	-40°C to +85°C
SY01	TPWRT	Power-up Period External Vcore Applied (Power-Up-Timer Active)	48	64	80	ms	-40°C to +85°C
SY02	TSYSDLY	System Delay Period: Time required to reload Device Configuration Fuses plus SYSCLK delay before first instruction is fetched.	—	1 μs + 8 SYSCLK cycles	—	—	-40°C to +85°C
SY20	TMCLR	MCLR Pulse Width (low)	—	2	—	μs	-40°C to +85°C
SY30	TBOR	BOR Pulse Width (low)	—	1	—	μs	-40°C to +85°C

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

PIC32MX3XX/4XX

NOTES:

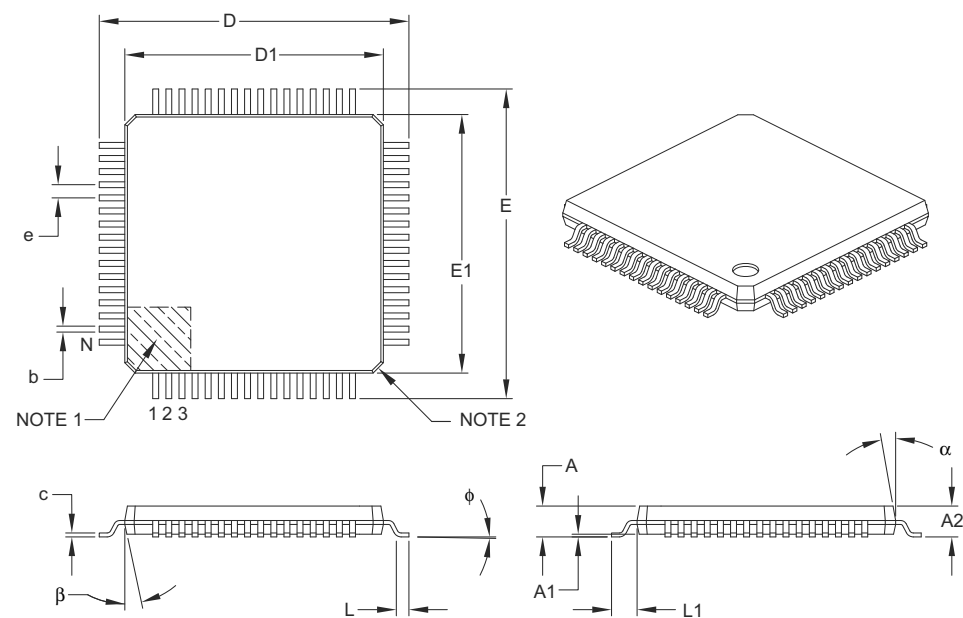
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30.2 Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.50 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

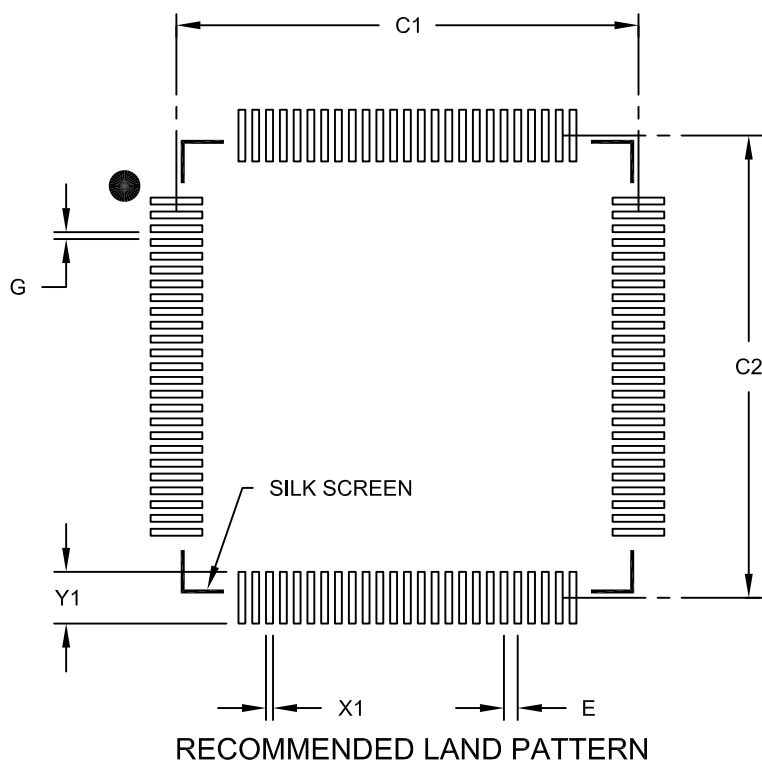
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

PIC32MX3XX/4XX

100-Lead Plastic Thin Quad Flatpack (PT)-12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B

PIC32MX3XX/4XX

TABLE A-3: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 29.0 “Electrical Characteristics”	Added the new V-Temp temperature range (-40°C to +105°C) to the heading of all specification tables. Updated the Ambient temperature under bias, updated the Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 2.3V, and added Voltage on V_{BUS} with respect to V_{SS} in Absolute Maximum Ratings. Added the characteristic, DC5a to Operating MIPS vs. Voltage (see Table 29-1). Updated or added the following parameters to the Operating Current (I_{DD}) DC Characteristics: DC20, DC23, DC24c, DC25d, DC26c (see Table 29-5). Added the following parameters to the Idle Current (I_{IDLE}) DC Characteristics: DC30c, DC31c, DC32c, DS33c, DC34c, DC35c, and DC36c (see Table 29-6). Added the following parameters to the Power-down Current (I_{PD}) DC Characteristics: DC40g, DC40h, DC40i, DC41g, DC41h, DC42g, DC42h, DC42i, DC43h, and DC43i (see Table 29-7). Added the Brown-out Reset (BOR) Electrical Characteristics (see Table 29-10). Removed all Conditions from the Program Memory DC Characteristics (see Table 29-11). Removed the AC Characteristics voltage reference table (Table 29-15). Added Note 2 to the PLL Clock Timing Specifications (see Table 29-18). Updated the OC/PWM Module Timing Characteristics (see Figure 29-9). Added parameter IM51 and Note 3 to the I2Cx Bus Data Timing Requirements (Master Mode) (see Table 29-32). Added parameter numbers (AD13, AD14, and AD15) to the ADC Module Specifications (see Table 29-34). Updated the 10-bit ADC Conversion Rate Parameters (see Table 29-35). Updated parameter AD57 (T_{SAMP}) in the Analog-to-Digital Conversion Timing Requirements (see Table 29-36). Updated the Conditions for parameters USB313, USB318, and USB319 in the OTG Electrical Specifications (see Table 29-40).
Section 30.0 “Packaging Information”	Updated the 64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] packing diagram.
Product Identification System	Added the new V-Temp (V) temperature information.

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